

N-Ch MOSFET

General Description

The WSP14N10 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSP14N10 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

Product Summery

BVDSS	RDSON	ID
100V	16mΩ	14A

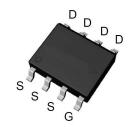
Applications

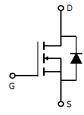
Load switch

Battery protection

Uninterruptible power supply

SOP-8 Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	14	А
I _{DM}	Pulsed Drain Current ²	42	Α
EAS	Single Pulse Avalanche Energy ³ L=0.1mH	30	mJ
P _D @T _A =25℃	Total Power Dissipation ⁴	72	W
T _{STG}	Storage Temperature Range	-55 to 150	$^{\circ}$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}$

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient ¹		40	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		24	°C/W



Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.098		V/℃
D	2	V _{GS} =10V , I _D =8A		16	20	0
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =6A		25	28	mΩ
V _{GS(th)}	Gate Threshold Voltage	\/ -\/ -250\	1.0	1.5	2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-5.52		mV/℃
ı	Drain Source Leakage Current	V _{DS} =100V , V _{GS} =0V , T _J =25℃			1	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =100V , V _{GS} =0V , T _J =55℃			5	uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, V_{DS} =0V			±100	nA
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		0.55	1.0	Ω
Qg	Total Gate Charge (10V)			19.8		
Q _{gs}	Gate-Source Charge	V _{DS} =50V , V _{GS} =10V , I _D =8A		2.4		nC
Q _{gd}	Gate-Drain Charge			5.3		
T _{d(on)}	Turn-On Delay Time			17.8		
Tr	Rise Time	V _{DD} =50V , V _{GS} =10V ,		3.9		
T _{d(off)}	Turn-Off Delay Time	R _G =2.2Ω I _D =10A		33.5		ns
T _f	Fall Time			3.2		
Ciss	Input Capacitance			1191		
C _{oss}	Output Capacitance	V _{DS} =50V , V _{GS} =0V , f=1MHz		195		pF
C _{rss}	Reverse Transfer Capacitance			41		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			40	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =8A , T _J =25℃			1.3	V
t _{rr}	Reverse Recovery Time			50		nS
Q _{rr}	Reverse Recovery Charge	∏F=8A , dl/dt=100A/μs , T J=25℃		95		nC

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a =25 °C.
- 5) V_{DD} =50 V, R_G =25 Ω , L=0.3 mH, starting T_j =25 $^{\circ}$ C.



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

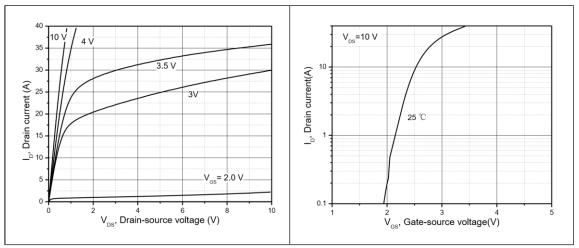


Figure 1, Typ. output characteristics

Figure 2, Typ. transfer characteristics

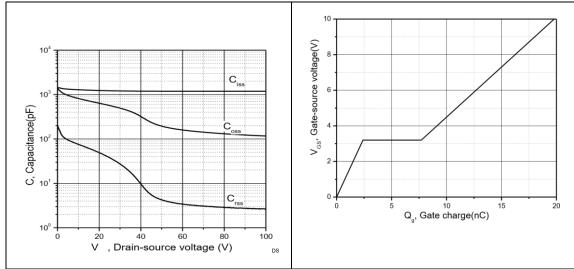


Figure 3, Typ. capacitances

Figure 4, Typ. gate charge

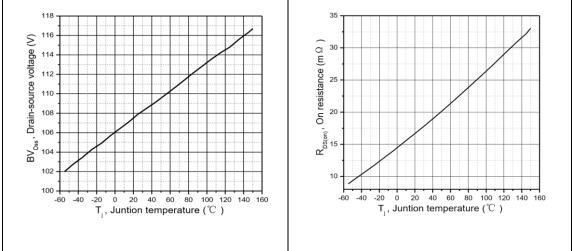
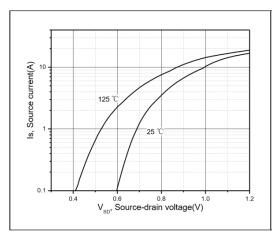


Figure 5, Drain-source breakdown voltage

Figure 6, Drain-source on-state resistance



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



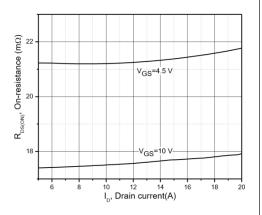


Figure 7, Forward characteristic of body diode

Figure 8, Drain-source on-state resistance

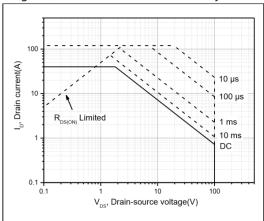
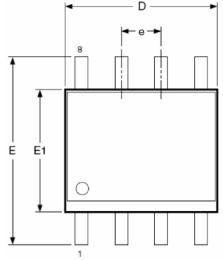
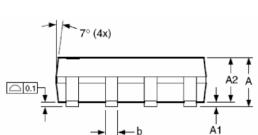


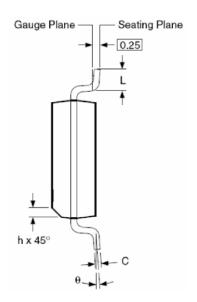
Figure 9, Safe operation area $T_C=25\,^{\circ}C$



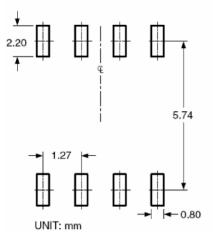
SOP-8 package







RECOMMENDED LAND PATTERN



Dimensions in millimeters

Symbols	Min.	Nom.	Max.
Α	1.35	1.65	1.75
A1	0.10	_	0.25
A2	1.25	1.50	1.65
b	0.31	_	0.51
С	0.17	_	0.25
D	4.80	4.90	5.00
E1	3.80	3.90	4.00
е	1.27 BSC		
E	5.80	6.00	6.20
h	0.25	_	0.50
L	0.40	_	1.27
θ	0°	_	8°

Dimensions in inches

Symbols	Min.	Nom.	Max.	
Α	0.053	0.065	0.069	
A1	0.004	_	0.010	
A2	0.049	0.059	0.065	
b	0.012	_	0.020	
С	0.007	_	0.010	
D	0.189	0.193	0.197	
E1	0.150	0.154	0.157	
е	0.050 BSC			
Е	0.228	0.236	0.244	
h	0.010	_	0.020	
L	0.016	_	0.050	
θ	0°	_	8°	



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